

[54] HEAT RELEASING PLATE FOR MOUNTING SEMICONDUCTOR COMPONENTS

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[**] Term: 14 Years

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[57] CLAIM

The ornamental design for heat releasing plate for mounting semiconductor components, as shown and described.

DESCRIPTION

FIG. 1 is a front view of the heat releasing plate for mounting semi-conductor components showing the new design;
FIG. 2 is a plan view thereof;
FIG. 3 is a bottom view thereof;
FIG. 4 is a right side view thereof; and
FIG. 5 is a sectional view taken on line 5—5 of FIG. 1.



